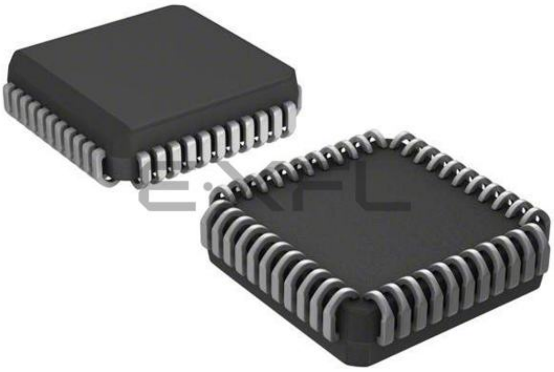


Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	30/20MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	64KB (64K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.6x16.6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts87c51rd2-lib

Mnemonic	Pin Number			Type	Name And Function
	DIL	LCC	VQFP 1.4		
V_{SS}	20	22	16	I	**Ground:** 0V reference
Vss1		1	39	I	**Optional Ground:** Contact the Sales Office for ground connection.
V_{CC}	40	44	38	I	**Power Supply:** This is the power supply voltage for normal, idle and power-down operation
P0.0-P0.7	39-32	43-36	37-30	I/O	**Port 0**: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high impedance inputs. Port 0 pins must be polarized to Vcc or Vss in order to prevent any parasitic current consumption. Port 0 is also the multiplexed low-order address and data bus during access to external program and data memory. In this application, it uses strong internal pull-up when emitting 1s. Port 0 also inputs the code bytes during EPROM programming. External pull-ups are required during program verification during which P0 outputs the code bytes.
P1.0-P1.7	1-8	2-9	40-44 1-3	I/O	**Port 1:** Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally pulled low will source current because of the internal pull-ups. Port 1 also receives the low-order address byte during memory programming and verification. Alternate functions for Port 1 include:
	1	2	40	I/O	**T2 (P1.0):** Timer/Counter 2 external count input/Clockout
	2	3	41	I	**T2EX (P1.1):** Timer/Counter 2 Reload/Capture/Direction Control
	3	4	42	I	**ECI (P1.2):** External Clock for the PCA
	4	5	43	I/O	**CEX0 (P1.3):** Capture/Compare External I/O for PCA module 0
	5	6	44	I/O	**CEX1 (P1.4):** Capture/Compare External I/O for PCA module 1
	6	7	45	I/O	**CEX0 (P1.5):** Capture/Compare External I/O for PCA module 2
	7	8	46	I/O	**CEX0 (P1.6):** Capture/Compare External I/O for PCA module 3
	8	9	47	I/O	**CEX0 (P1.7):** Capture/Compare External I/O for PCA module 4
P2.0-P2.7	21-28	24-31	18-25	I/O	**Port 2**: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally pulled low will source current because of the internal pull-ups. Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR).In this application, it uses strong internal pull-ups emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), port 2 emits the contents of the P2 SFR. Some Port 2 pins (P2.0 to P2.5) receive the high order address bits during EPROM programming and verification:
P3.0-P3.7	10-17	11, 13-19	5, 7-13	I/O	**Port 3:** Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally pulled low will source current because of the internal pull-ups. Some Port 3 pins (P3.4 to P3.5) receive the high order address bits during EPROM programming and verification. Port 3 also serves the special features of the 80C51 family, as listed below.
	10	11	5	I	**RXD (P3.0):** Serial input port
	11	13	7	O	**TXD (P3.1):** Serial output port
	12	14	8	I	**$\overline{\text{INT0}}$ (P3.2):** External interrupt 0
	13	15	9	I	**$\overline{\text{INT1}}$ (P3.3):** External interrupt 1
	14	16	10	I	**T0 (P3.4):** Timer 0 external input
	15	17	11	I	**T1 (P3.5):** Timer 1 external input
	16	18	12	O	**$\overline{\text{WR}}$ (P3.6):** External data memory write strobe
	17	19	13	O	**$\overline{\text{RD}}$ (P3.7):** External data memory read strobe

Mnemonic	Pin Number			Type	Name And Function
ALE/$\overline{\text{PROG}}$	30	33	27	O (I)	**Address Latch Enable/Program Pulse:** Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. This pin is also the program pulse input ($\overline{\text{PROG}}$) during EPROM programming. ALE can be disabled by setting SFR's AUXR.0 bit. With this bit set, ALE will be inactive during internal fetches.
$\overline{\text{PSEN}}$	29	32	26	O	**Program Store ENable:** The read strobe to external program memory. When executing code from the external program memory, $\overline{\text{PSEN}}$ is activated twice each machine cycle, except that two $\overline{\text{PSEN}}$ activations are skipped during each access to external data memory. $\overline{\text{PSEN}}$ is not activated during fetches from internal program memory.
$\overline{\text{EA}}$/V_{PP}	31	35	29	I	**External Access Enable/Programming Supply Voltage:** $\overline{\text{EA}}$ must be externally held low to enable the device to fetch code from external program memory locations 0000H and 3FFFH (RB) or 7FFFH (RC), or FFFFH (RD). If EA is held high, the device executes from internal program memory unless the program counter contains an address greater than 3FFFH (RB) or 7FFFH (RC) $\overline{\text{EA}}$ must be held low for ROMless devices. This pin also receives the 12.75V programming supply voltage (V_{PP}) during EPROM programming. If security level 1 is programmed, $\overline{\text{EA}}$ will be internally latched on Reset.
XTAL1	19	21	15	I	**Crystal 1:** Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	18	20	14	O	**Crystal 2:** Output from the inverting oscillator amplifier

ASSEMBLY LANGUAGE

```
; Block move using dual data pointers
; Destroys DPTR0, DPTR1, A and PSW
; note: DPS exits opposite of entry state
; unless an extra INC AUXR1 is added
;
00A2                AUXR1 EQU 0A2H
;
0000  909000        MOV  DPTR,#SOURCE          ; address of SOURCE
0003  05A2          INC  AUXR1                 ; switch data pointers
0005  90A000        MOV  DPTR,#DEST            ; address of DEST
0008                LOOP:
0008  05A2          INC  AUXR1                 ; switch data pointers
000A  E0            MOVX A,@DPTR               ; get a byte from SOURCE
000B  A3            INC  DPTR                  ; increment SOURCE address
000C  05A2          INC  AUXR1                 ; switch data pointers
000E  F0            MOVX @DPTR,A               ; write the byte to DEST
000F  A3            INC  DPTR                  ; increment DEST address
0010  70F6          JNZ  LOOP                  ; check for 0 terminator
0012  05A2          INC  AUXR1                 ; (optional) restore DPS
```

INC is a short (2 bytes) and fast (12 clocks) way to manipulate the DPS bit in the AUXR1 SFR. However, note that the INC instruction does not directly force the DPS bit to a particular state, but simply toggles it. In simple routines, such as the block move example, only the fact that DPS is toggled in the proper sequence matters, not its actual value. In other words, the block move routine works the same whether DPS is '0' or '1' on entry. Observe that without the last instruction (INC AUXR1), the routine will exit with DPS in the opposite state.

6.3. Expanded RAM (XRAM)

The TS80C51Rx2 provide additional Bytes of ramdom access memory (RAM) space for increased data parameter handling and high level language usage.

RA2, RB2 and RC2 devices have 256 bytes of expanded RAM, from 00H to FFH in external data space; RD2 devices have 768 bytes of expanded RAM, from 00H to 2FFH in external data space.

The TS80C51Rx2 has internal data memory that is mapped into four separate segments.

The four segments are:

- 1. The Lower 128 bytes of RAM (addresses 00H to 7FH) are directly and indirectly addressable.
- 2. The Upper 128 bytes of RAM (addresses 80H to FFH) are indirectly addressable only.
- 3. The Special Function Registers, SFRs, (addresses 80H to FFH) are directly addressable only.
- 4. The expanded RAM bytes are indirectly accessed by MOVX instructions, and with the EXTRAM bit cleared in the AUXR register. (See Table 5.)

The Lower 128 bytes can be accessed by either direct or indirect addressing. The Upper 128 bytes can be accessed by indirect addressing only. The Upper 128 bytes occupy the same address space as the SFR. That means they have the same address, but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the CPU knows whether the access is to the upper 128 bytes of data RAM or to SFR space by the addressing mode used in the instruction.

- Instructions that use direct addressing access SFR space. **For example: MOV 0A0H, # data** ,accesses the SFR at location 0A0H (which is P2).
- Instructions that use indirect addressing access the Upper 128 bytes of data RAM. **For example: MOV @R0, # data** where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).
- The 256 or 768 XRAM bytes can be accessed by indirect addressing, with EXTRAM bit cleared and MOVX instructions. This part of memory which is physically located on-chip, logically occupies the first 256 or 768 bytes of external data memory.
- With EXTRAM = 0, the XRAM is indirectly addressed, using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. **An access to XRAM will not affect ports P0, P2, P3.6 ($\overline{WR}$) and P3.7 ($\overline{RD}$)**. **For example, with EXTRAM = 0, MOVX @R0, # data** where R0 contains 0A0H, accesses the XRAM at address 0A0H rather than external memory. An access to external data memory locations higher than FFH (i.e. 0100H to FFFFH) (higher than 2FFH (i.e. 0300H to FFFFH for RD devices) will be performed with the MOVX DPTR instructions in the same way as in the standard 80C51, so with P0 and P2 as data/address busses, and P3.6 and P3.7 as write and read timing signals. Refer to Figure . For RD devices, accesses to expanded RAM from 100H to 2FFH can only be done thanks to the use of DPTR.
- With EXTRAM = 1, MOVX @Ri and MOVX @DPTR will be similar to the standard 80C51. MOVX @ Ri will provide an eight-bit address multiplexed with data on Port0 and any output port pins can be used to output higher order address bits. This is to provide the external paging capability. MOVX @DPTR will generate a sixteen-bit address. Port2 outputs the high-order eight address bits (the contents of DPH) while Port0 multiplexes the low-order eight address bits (DPL) with data. MOVX @ Ri and MOVX @DPTR will generate either read or write signals on P3.6 ($\overline{WR}$) and P3.7 ($\overline{RD}$).

The stack pointer (SP) may be located anywhere in the 256 bytes RAM (lower and upper RAM) internal data memory. The stack may not be located in the XRAM.

Software may examine FE bit after each reception to check for data errors. Once set, only software or a reset can clear FE bit. Subsequently received frames with valid stop bits cannot clear FE bit. When FE feature is enabled, RI rises on stop bit instead of the last data bit (See Figure 14. and Figure 15.).

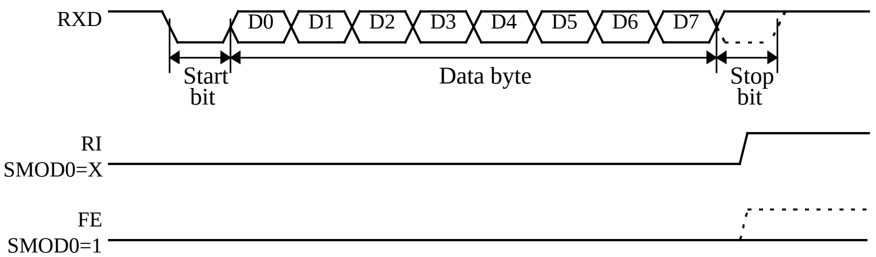


Figure 14. UART Timings in Mode 1

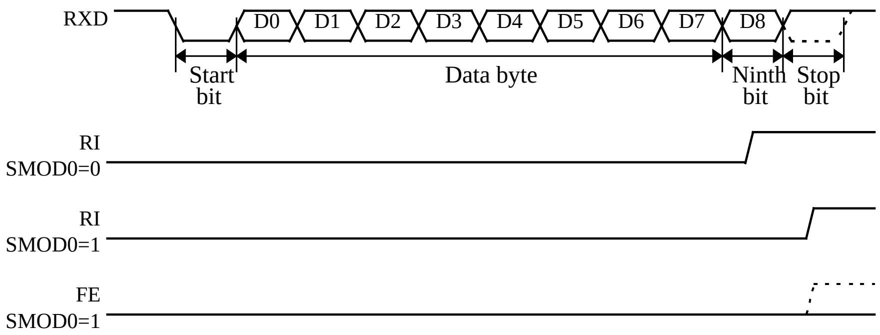


Figure 15. UART Timings in Modes 2 and 3

6.6.2. Automatic Address Recognition

The automatic address recognition feature is enabled when the multiprocessor communication feature is enabled (SM2 bit in SCON register is set).

Implemented in hardware, automatic address recognition enhances the multiprocessor communication feature by allowing the serial port to examine the address of each incoming command frame. Only when the serial port recognizes its own address, the receiver sets RI bit in SCON register to generate an interrupt. This ensures that the CPU is not interrupted by command frames addressed to other devices.

If desired, you may enable the automatic address recognition feature in mode 1. In this configuration, the stop bit takes the place of the ninth data bit. Bit RI is set only when the received command frame address matches the device’s address and is terminated by a valid stop bit.

To support automatic address recognition, a device is identified by a given address and a broadcast address.

NOTE: The multiprocessor communication and automatic address recognition features cannot be enabled in mode 0 (i.e. setting SM2 bit in SCON register in mode 0 has no effect).

Table 18. Priority Level Bit Values

IPH.x	IP.x	Interrupt Level Priority
0	0	0 (Lowest)
0	1	1
1	0	2
1	1	3 (Highest)

A low-priority interrupt can be interrupted by a high priority interrupt, but not by another low-priority interrupt. A high-priority interrupt can't be interrupted by any other interrupt source.

If two interrupt requests of different priority levels are received simultaneously, the request of higher priority level is serviced. If interrupt requests of the same priority level are received simultaneously, an internal polling sequence determines which request is serviced. Thus within each priority level there is a second priority structure determined by the polling sequence.

Table 19. IE Register

IE - Interrupt Enable Register (A8h)

7	6	5	4	3	2	1	0
EA	**EC**	**ET2**	**ES**	**ET1**	**EX1**	**ET0**	**EX0**

Bit Number	Bit Mnemonic	Description
7	EA	**Enable All interrupt bit** Clear to disable all interrupts. Set to enable all interrupts. If EA=1, each interrupt source is individually enabled or disabled by setting or clearing its own interrupt enable bit.
6	EC	**PCA interrupt enable bit** Clear to disable . Set to enable.
5	ET2	**Timer 2 overflow interrupt Enable bit** Clear to disable timer 2 overflow interrupt. Set to enable timer 2 overflow interrupt.
4	ES	**Serial port Enable bit** Clear to disable serial port interrupt. Set to enable serial port interrupt.
3	ET1	**Timer 1 overflow interrupt Enable bit** Clear to disable timer 1 overflow interrupt. Set to enable timer 1 overflow interrupt.
2	EX1	**External interrupt 1 Enable bit** Clear to disable external interrupt 1. Set to enable external interrupt 1.
1	ET0	**Timer 0 overflow interrupt Enable bit** Clear to disable timer 0 overflow interrupt. Set to enable timer 0 overflow interrupt.
0	EX0	**External interrupt 0 Enable bit** Clear to disable external interrupt 0. Set to enable external interrupt 0.

Reset Value = 0000 0000b
Bit addressable

Table 24. WDTPRG Register

WDTPRG Address (0A7h)

7	6	5	4	3	2	1	0
T4	**T3**	**T2**	**T1**	**T0**	**S2**	**S1**	**S0**

Bit Number	Bit Mnemonic	Description
7	T4	**Reserved** Do not try to set or clear this bit.
6	T3	
5	T2	
4	T1	
3	T0	
2	S2	**WDT Time-out select bit 2**
1	S1	**WDT Time-out select bit 1**
0	S0	**WDT Time-out select bit 0**

S2	S1	S0	Selected Time-out
0	0	0	(2^{14} - 1) machine cycles, 16.3 ms @ 12 MHz
0	0	1	(2^{15} - 1) machine cycles, 32.7 ms @ 12 MHz
0	1	0	(2^{16} - 1) machine cycles, 65.5 ms @ 12 MHz
0	1	1	(2^{17} - 1) machine cycles, 131 ms @ 12 MHz
1	0	0	(2^{18} - 1) machine cycles, 262 ms @ 12 MHz
1	0	1	(2^{19} - 1) machine cycles, 542 ms @ 12 MHz
1	1	0	(2^{20} - 1) machine cycles, 1.05 s @ 12 MHz
1	1	1	(2^{21} - 1) machine cycles, 2.09 s @ 12 MHz

Reset value XXXX X000

6.10.2. WDT during Power Down and Idle

In Power Down mode the oscillator stops, which means the WDT also stops. While in Power Down mode the user does not need to service the WDT. There are 2 methods of exiting Power Down mode: by a hardware reset or via a level activated external interrupt which is enabled prior to entering Power Down mode. When Power Down is exited with hardware reset, servicing the WDT should occur as it normally should whenever the TS80C51Rx2 is reset. Exiting Power Down with an interrupt is significantly different. The interrupt is held low long enough for the oscillator to stabilize. When the interrupt is brought high, the interrupt is serviced. To prevent the WDT from resetting the device while the interrupt pin is held low, the WDT is not started until the interrupt is pulled high. It is suggested that the WDT be reset during the interrupt service routine.

To ensure that the WDT does not overflow within a few states of exiting of powerdown, it is best to reset the WDT just before entering powerdown.

In the Idle mode, the oscillator continues to run. To prevent the WDT from resetting the TS80C51Rx2 while in Idle mode, the user should always set up a timer that will periodically exit Idle, service the WDT, and re-enter Idle mode.

8.3. EPROM Programming

8.3.1. Set-up modes

In order to program and verify the EPROM or to read the signature bytes, the TS87C51RB2/RC2/RD2 is placed in specific set-up modes (See Figure 18.).

Control and program signals must be held at the levels indicated in Table 30.

8.3.2. Definition of terms

Address Lines: P1.0-P1.7, P2.0-P2.5, P3.4, P3.5 respectively for A0-A15 (P2.5 (A13) for RB, P3.4 (A14) for RC, P3.5 (A15) for RD)

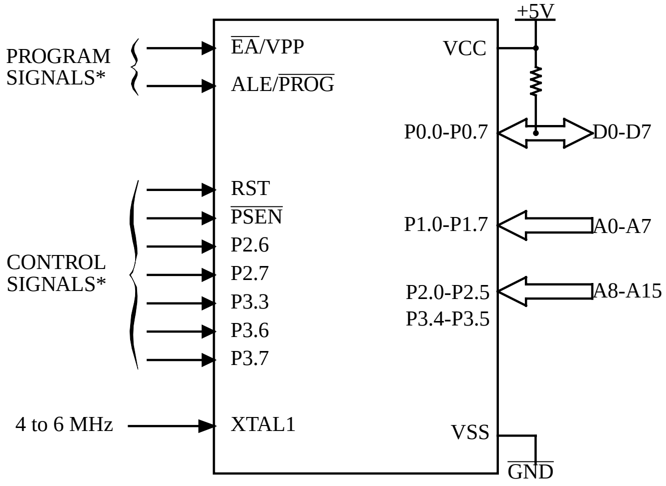
Data Lines: P0.0-P0.7 for D0-D7

Control Signals: RST, $\overline{\text{PSEN}}$, P2.6, P2.7, P3.3, P3.6, P3.7.

Program Signals: ALE/$\overline{\text{PROG}}$, $\overline{\text{EA}}$/VPP.

Table 30. EPROM Set-Up Modes

Mode	RST	PSEN	ALE/ $\overline{\text{PROG}}$	$\overline{\text{EA}}$/VPP	P2.6	P2.7	P3.3	P3.6	P3.7
Program Code data	1	0	⊔	12.75V	0	1	1	1	1
Verify Code data	1	0	1	1	0	⊔	0	1	1
Program Encryption Array Address 0-3Fh	1	0	⊔	12.75V	0	1	1	0	1
Read Signature Bytes	1	0	1	1	0	⊔	0	0	0
Program Lock bit 1	1	0	⊔	12.75V	1	1	1	1	1
Program Lock bit 2	1	0	⊔	12.75V	1	1	1	0	0
Program Lock bit 3	1	0	⊔	12.75V	1	0	1	1	0



* See Table 31. for proper value on these inputs

Figure 18. Set-Up Modes Configuration

8.3.3. Programming Algorithm

The Improved Quick Pulse algorithm is based on the Quick Pulse algorithm and decreases the number of pulses applied during byte programming from 25 to 1.

To program the TS87C51RB2/RC2/RD2 the following sequence must be exercised:

- Step 1: Activate the combination of control signals.
- Step 2: Input the valid address on the address lines.
- Step 3: Input the appropriate data on the data lines.
- Step 4: Raise $\overline{\text{EA}}$/VPP from VCC to VPP (typical 12.75V).
- Step 5: Pulse ALE/$\overline{\text{PROG}}$ once.
- Step 6: Lower $\overline{\text{EA}}$/VPP from VPP to VCC

Repeat step 2 through 6 changing the address and data for the entire array or until the end of the object file is reached (See Figure 19.).

8.3.4. Verify algorithm

Code array verify must be done after each byte or block of bytes is programmed. In either case, a complete verify of the programmed array will ensure reliable programming of the TS87C51RB2/RC2/RD2.

P 2.7 is used to enable data output.

To verify the TS87C51RB2/RC2/RD2 code the following sequence must be exercised:

- Step 1: Activate the combination of program and control signals.
- Step 2: Input the valid address on the address lines.
- Step 3: Read data on the data lines.

Repeat step 2 through 3 changing the address for the entire array verification (See Figure 19.)

The encryption array cannot be directly verified. Verification of the encryption array is done by observing that the code array is well encrypted.

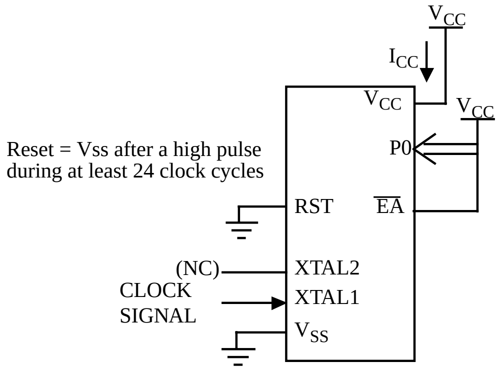
Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
I_{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			3 + 0.6 Freq (MHz) @12MHz 10.2 @16MHz 12.6	mA	V_{CC} = 5.5 V(8)
I_{CC} idle	Power Supply Current Maximum values, X1 mode: (7)			0.25+0.3 Freq (MHz) @12MHz 3.9 @16MHz 5.1	mA	V_{CC} = 5.5 V(2)

10.4. DC Parameters for Low Voltage

T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V ± 10%; F = 0 to 30 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V ± 10%; F = 0 to 30 MHz.

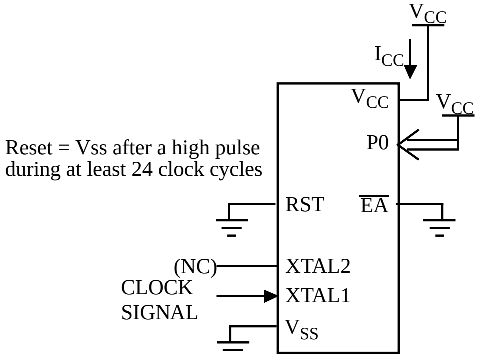
Table 33. DC Parameters for Low Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3, 4, 5 (6)			0.45	V	I_{OL} = 0.8 mA(4)
V_{OL1}	Output Low Voltage, port 0, ALE, $\overline{PSEN}$ (6)			0.45	V	I_{OL} = 1.6 mA(4)
V_{OH}	Output High Voltage, ports 1, 2, 3, 4, 5	0.9 V_{CC}			V	I_{OH} = -10 µA
V_{OH1}	Output High Voltage, port 0, ALE, $\overline{PSEN}$	0.9 V_{CC}			V	I_{OH} = -40 µA
I_{IL}	Logical 0 Input Current ports 1, 2, 3, 4, 5			-50	µA	Vin = 0.45 V
I_{LI}	Input Leakage Current			±10	µA	0.45 V < Vin < V_{CC}
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3, 4, 5			-650	µA	Vin = 2.0 V
R_{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
CIO	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz T_A = 25°C
I_{PD}	Power Down Current		20 (5) 10 (5)	50 30	µA	V_{CC} = 2.0 V to 5.5 V(3) V_{CC} = 2.0 V to 3.3 V(3)
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.2 Freq (MHz) @12MHz 3.4 @16MHz 4.2	mA	V_{CC} = 3.3 V(1)
I_{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.3 Freq (MHz) @12MHz 4.6 @16MHz 5.8	mA	V_{CC} = 3.3 V(8)



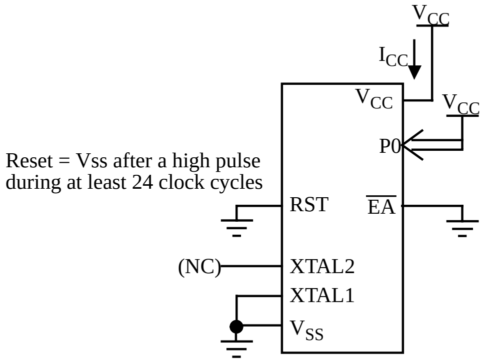
All other pins are disconnected.

Figure 21. Operating I_{CC} Test Condition



All other pins are disconnected.

Figure 22. I_{CC} Test Condition, Idle Mode



All other pins are disconnected.

Figure 23. I_{CC} Test Condition, Power-Down Mode

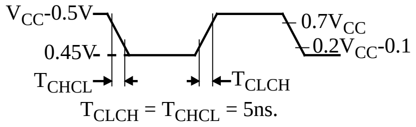


Figure 24. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes

10.5. AC Parameters

10.5.1. Explanation of the AC Symbols

Each timing symbol has 5 characters. The first character is always a “T” (stands for time). The other characters, depending on their positions, stand for the name of a signal or the logical status of that signal. The following is a list of all the characters and what they stand for.

Example:T_{AVLL} = Time for Address Valid to ALE Low.
T_{LLPL} = Time for ALE Low to $\overline{\text{PSEN}}$ Low.

TA = 0 to +70°C (commercial temperature range); V_{SS} = 0 V; V_{CC} = 5 V ± 10%; -M and -V ranges.
TA = -40°C to +85°C (industrial temperature range); V_{SS} = 0 V; V_{CC} = 5 V ± 10%; -M and -V ranges.
TA = 0 to +70°C (commercial temperature range); V_{SS} = 0 V; 2.7 V < V_{CC} < 5.5 V; -L range.
TA = -40°C to +85°C (industrial temperature range); V_{SS} = 0 V; 2.7 V < V_{CC} < 5.5 V; -L range.

Table 34. gives the maximum applicable load capacitance for Port 0, Port 1, 2 and 3, and ALE and $\overline{\text{PSEN}}$ signals. Timings will be guaranteed if these capacitances are respected. Higher capacitance values can be used, but timings will then be degraded.

Table 34. Load Capacitance versus speed range, in pF

	-M	**-V**	**-L**
Port 0	100	50	100
Port 1, 2, 3	80	50	80
ALE / $\overline{\text{PSEN}}$	100	30	100

Table 36., Table 39. and Table 42. give the description of each AC symbols.

Table 37., Table 40. and Table 43. give for each range the AC parameter.

Table 38., Table 41. and Table 44. give the frequency derating formula of the AC parameter. To calculate each AC symbols, take the x value corresponding to the speed grade you need (-M, -V or -L) and replace this value in the formula. Values of the frequency must be limited to the corresponding speed grade:

Table 35. Max frequency for derating formula regarding the speed grade

	-M X1 mode	**-M X2 mode**	**-V X1 mode**	**-V X2 mode**	**-L X1 mode**	**-L X2 mode**
Freq (MHz)	40	20	40	30	30	20
T (ns)	25	50	25	33.3	33.3	50

Example:
T_{LLIV} in X2 mode for a -V part at 20 MHz (T = $1/20^{E6}$ = 50 ns):
x= 22 (Table 38.)
T= 50ns
T_{LLIV}= 2T - x = 2 x 50 - 22 = 78ns

10.5.2. External Program Memory Characteristics

Table 36. Symbol Description

Symbol	Parameter
T	Oscillator clock period
T_{LHLL}	ALE pulse width
T_{AVLL}	Address Valid to ALE
T_{LLAX}	Address Hold After ALE
T_{LLIV}	ALE to Valid Instruction In
T_{LLPL}	ALE to $\overline{PSEN}$
T_{PLPH}	$\overline{PSEN}$ Pulse Width
T_{PLIV}	$\overline{PSEN}$ to Valid Instruction In
T_{PXIX}	Input Instruction Hold After $\overline{PSEN}$
T_{PXIZ}	Input Instruction FloatAfter $\overline{PSEN}$
T_{PXAV}	$\overline{PSEN}$ to Address Valid
T_{AVIV}	Address to Valid Instruction In
T_{PLAZ}	$\overline{PSEN}$ Low to Address Float

Table 37. AC Parameters for Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T	25		33		25		50		33		ns
T_{LHLL}	40		25		42		35		52		ns
T_{AVLL}	10		4		12		5		13		ns
T_{LLAX}	10		4		12		5		13		ns
T_{LLIV}		70		45		78		65		98	ns
T_{LLPL}	15		9		17		10		18		ns
T_{PLPH}	55		35		60		50		75		ns
T_{PLIV}		35		25		50		30		55	ns
T_{PXIX}	0		0		0		0		0		ns
T_{PXIZ}		18		12		20		10		18	ns
T_{AVIV}		85		53		95		80		122	ns
T_{PLAZ}		10		10		10		10		10	ns

Table 38. AC Parameters for a Variable Clock: derating formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{LHLL}	Min	2 T - x	T - x	10	8	15	ns
T_{AVLL}	Min	T - x	0.5 T - x	15	13	20	ns
T_{LLAX}	Min	T - x	0.5 T - x	15	13	20	ns
T_{LLIV}	Max	4 T - x	2 T - x	30	22	35	ns
T_{LLPL}	Min	T - x	0.5 T - x	10	8	15	ns
T_{PLPH}	Min	3 T - x	1.5 T - x	20	15	25	ns
T_{PLIV}	Max	3 T - x	1.5 T - x	40	25	45	ns
T_{PXIX}	Min	x	x	0	0	0	ns
T_{PXIZ}	Max	T - x	0.5 T - x	7	5	15	ns
T_{AVIV}	Max	5 T - x	2.5 T - x	40	30	45	ns
T_{PLAZ}	Max	x	x	10	10	10	ns

10.5.3. External Program Memory Read Cycle

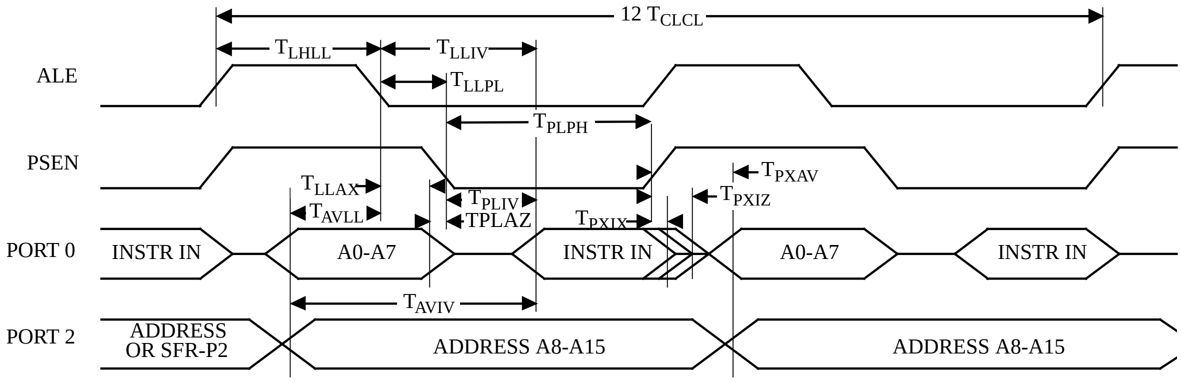


Figure 25. External Program Memory Read Cycle

Table 40. AC Parameters for a Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T_{RLRH}	130		85		135		125		175		ns
T_{WLWH}	130		85		135		125		175		ns
T_{RLDV}		100		60		102		95		137	ns
T_{RHDX}	0		0		0		0		0		ns
T_{RHDZ}		30		18		35		25		42	ns
T_{LLDV}		160		98		165		155		222	ns
T_{AVDV}		165		100		175		160		235	ns
T_{LLWL}	50	100	30	70	55	95	45	105	70	130	ns
T_{AVWL}	75		47		80		70		103		ns
T_{QVWX}	10		7		15		5		13		ns
T_{QVWH}	160		107		165		155		213		ns
T_{WHQX}	15		9		17		10		18		ns
T_{RLAZ}		0		0		0		0		0	ns
T_{WHLH}	10	40	7	27	15	35	5	45	13	53	ns

Table 41. AC Parameters for a Variable Clock: derating formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{RLRH}	Min	6 T - x	3 T - x	20	15	25	ns
T_{WLWH}	Min	6 T - x	3 T - x	20	15	25	ns
T_{RLDV}	Max	5 T - x	2.5 T - x	25	23	30	ns
T_{RHDX}	Min	x	x	0	0	0	ns
T_{RHDZ}	Max	2 T - x	T - x	20	15	25	ns
T_{LLDV}	Max	8 T - x	4T -x	40	35	45	ns
T_{AVDV}	Max	9 T - x	4.5 T - x	60	50	65	ns
T_{LLWL}	Min	3 T - x	1.5 T - x	25	20	30	ns
T_{LLWL}	Max	3 T + x	1.5 T + x	25	20	30	ns
T_{AVWL}	Min	4 T - x	2 T - x	25	20	30	ns
T_{QVWX}	Min	T - x	0.5 T - x	15	10	20	ns
T_{QVWH}	Min	7 T - x	3.5 T - x	15	10	20	ns
T_{WHQX}	Min	T - x	0.5 T - x	10	8	15	ns
T_{RLAZ}	Max	x	x	0	0	0	ns
T_{WHLH}	Min	T - x	0.5 T - x	15	10	20	ns
T_{WHLH}	Max	T + x	0.5 T + x	15	10	20	ns

10.5.5. External Data Memory Write Cycle

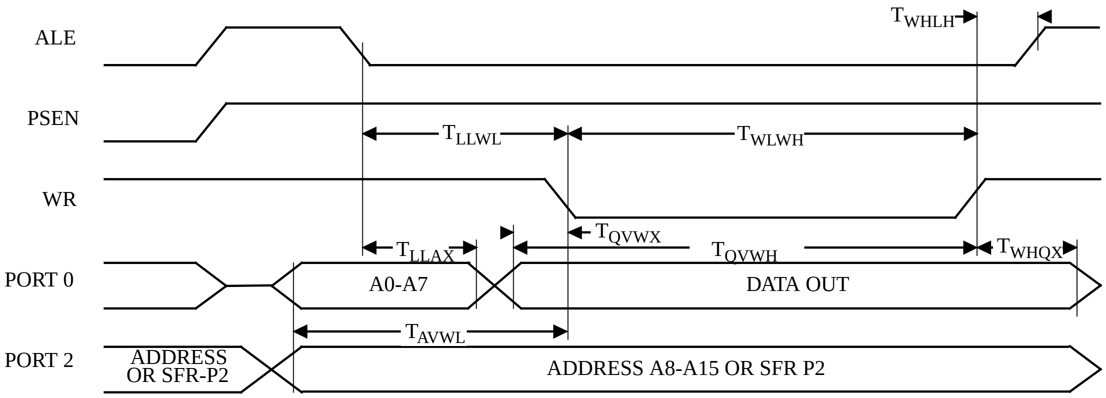


Figure 26. External Data Memory Write Cycle

10.5.6. External Data Memory Read Cycle

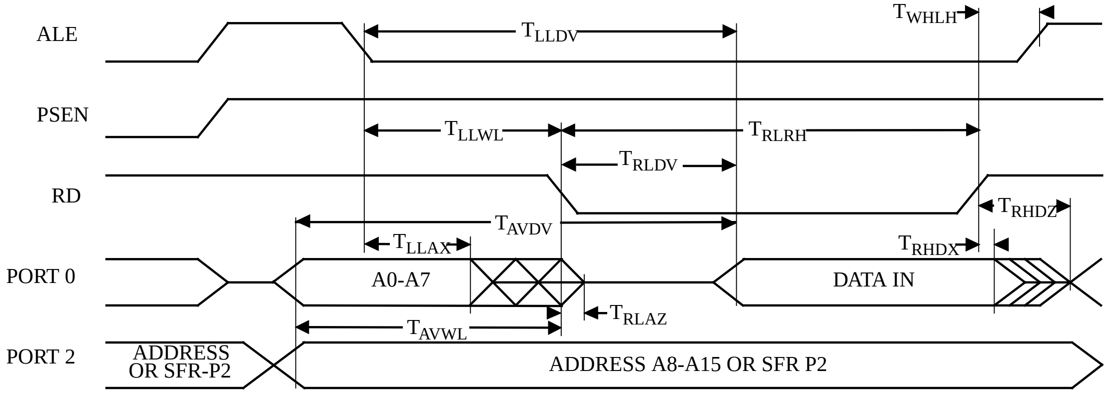


Figure 27. External Data Memory Read Cycle

10.5.7. Serial Port Timing - Shift Register Mode

Table 42. Symbol Description

Symbol	Parameter
T_{XLXL}	Serial port clock cycle time
T_{QVHX}	Output data set-up to clock rising edge
T_{XHQX}	Output data hold after clock rising edge
T_{XHDX}	Input data hold after clock rising edge
T_{XHDV}	Clock rising edge to input data valid

Table 43. AC Parameters for a Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
T_{XLXL}	300		200		300		300		400		ns
T_{QVHX}	200		117		200		200		283		ns
T_{XHQX}	30		13		30		30		47		ns
T_{XHDX}	0		0		0		0		0		ns
T_{XHDV}		117		34		117		117		200	ns

Table 44. AC Parameters for a Variable Clock: derating formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{XLXL}	Min	12 T	6 T				ns
T_{QVHX}	Min	10 T - x	5 T - x	50	50	50	ns
T_{XHQX}	Min	2 T - x	T - x	20	20	20	ns
T_{XHDX}	Min	x	x	0	0	0	ns
T_{XHDV}	Max	10 T - x	5 T- x	133	133	133	ns

10.5.8. Shift Register Timing Waveforms

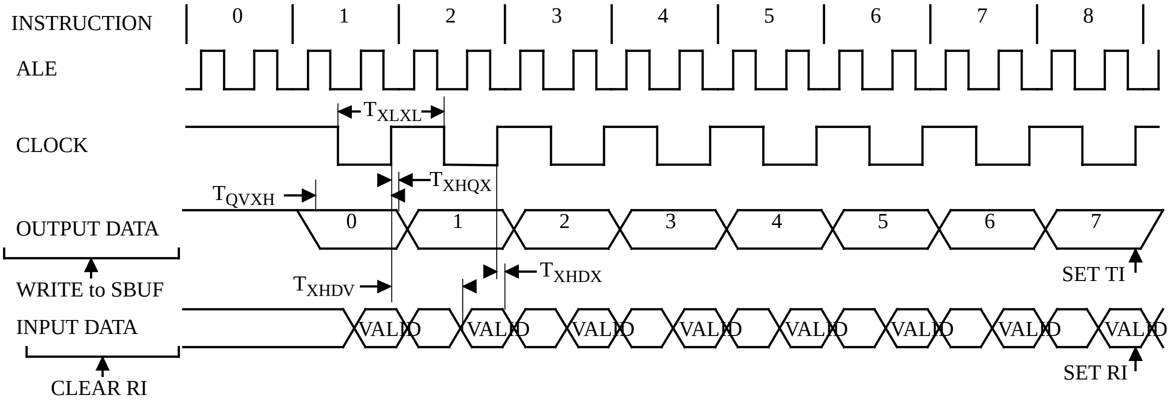


Figure 28. Shift Register Timing Waveforms

10.5.11. External Clock Drive Characteristics (XTAL1)

Table 46. AC Parameters

Symbol	Parameter	Min	Max	Units
T_{CLCL}	Oscillator Period	25		ns
T_{CHCX}	High Time	5		ns
T_{CLCX}	Low Time	5		ns
T_{CLCH}	Rise Time		5	ns
T_{CHCL}	Fall Time		5	ns
T_{CHCX}/T_{CLCX}	Cyclic ratio in X2 mode	40	60	%

10.5.12. External Clock Drive Waveforms

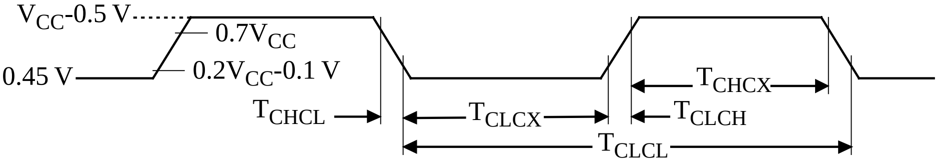


Figure 30. External Clock Drive Waveforms

10.5.13. AC Testing Input/Output Waveforms

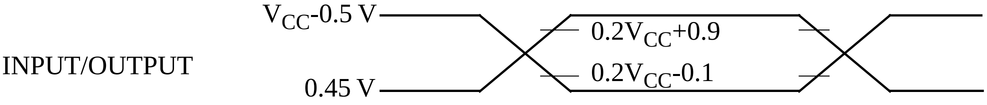


Figure 31. AC Testing Input/Output Waveforms

AC inputs during testing are driven at V_{CC} - 0.5 for a logic “1” and 0.45V for a logic “0”. Timing measurement are made at V_{IH} min for a logic “1” and V_{IL} max for a logic “0”.

10.5.14. Float Waveforms

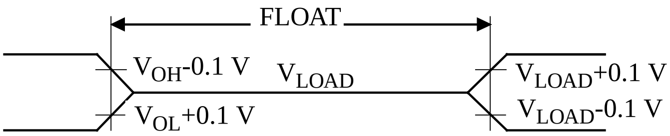
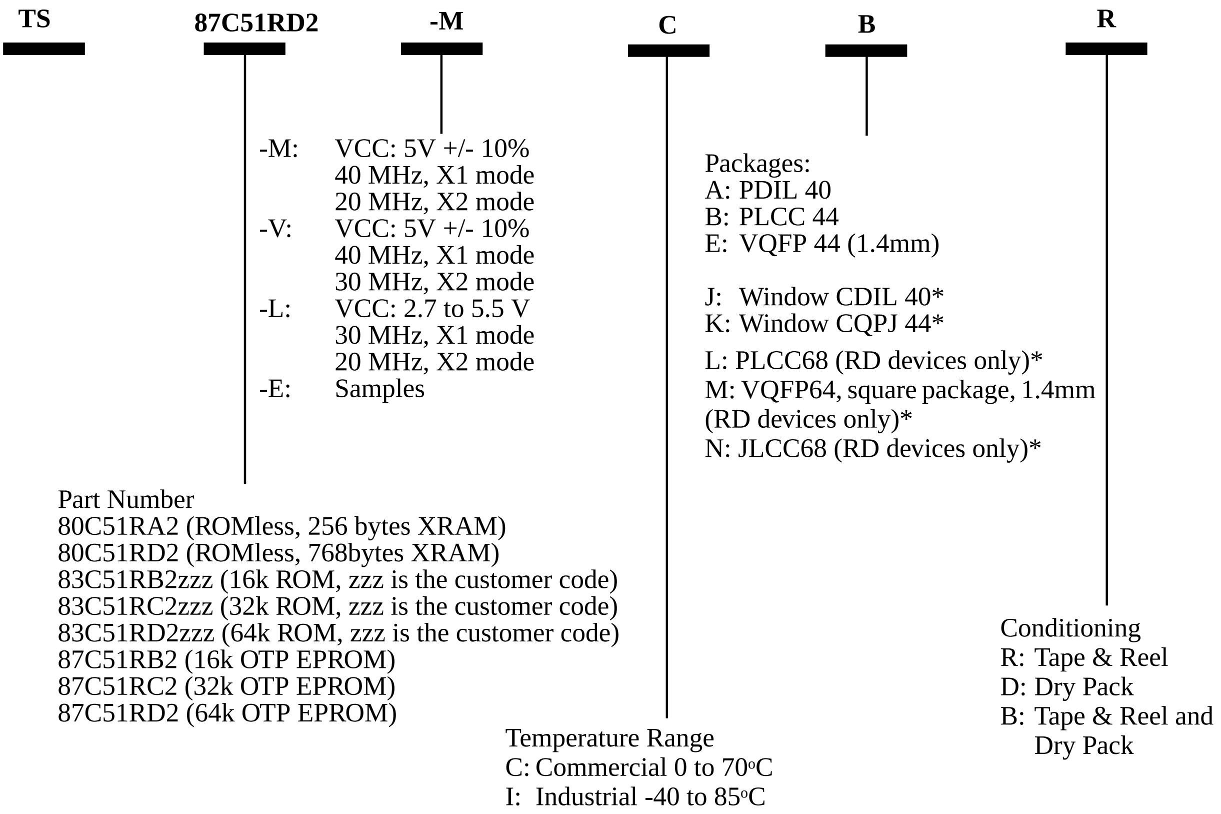


Figure 32. Float Waveforms

11. Ordering Information



-M: VCC: 5V +/- 10%
40 MHz, X1 mode
20 MHz, X2 mode
-V: VCC: 5V +/- 10%
40 MHz, X1 mode
30 MHz, X2 mode
-L: VCC: 2.7 to 5.5 V
30 MHz, X1 mode
20 MHz, X2 mode
-E: Samples

Packages:
A: PDIL 40
B: PLCC 44
E: VQFP 44 (1.4mm)

J: Window CDIL 40*
K: Window CQPJ 44*
L: PLCC68 (RD devices only)*
M: VQFP64, square package, 1.4mm (RD devices only)*
N: JLCC68 (RD devices only)*

Part Number
80C51RA2 (ROMless, 256 bytes XRAM)
80C51RD2 (ROMless, 768bytes XRAM)
83C51RB2zzz (16k ROM, zzz is the customer code)
83C51RC2zzz (32k ROM, zzz is the customer code)
83C51RD2zzz (64k ROM, zzz is the customer code)
87C51RB2 (16k OTP EPROM)
87C51RC2 (32k OTP EPROM)
87C51RD2 (64k OTP EPROM)

Temperature Range
C: Commercial 0 to 70°C
I: Industrial -40 to 85°C

Conditioning
R: Tape & Reel
D: Dry Pack
B: Tape & Reel and Dry Pack

(*) Check with Atmel Wireless & Microcontrollers Sales Office for availability. Ceramic packages (J, K, N) are available for proto
typing, not for volume production. Ceramic packages are available for OTP only.

Table 47. Maximum Clock Frequency

Code	-M	-V	-L	Unit
Standard Mode, oscillator frequency	40	40	30	MHz
Standard Mode, internal frequency	40	40	30	
X2 Mode, oscillator frequency	20	30	20	MHz
X2 Mode, internal equivalent frequency	40	**60**	**40**	